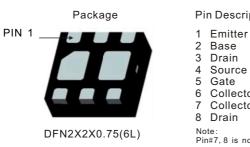
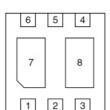
瑞信半導體有限公司 MegaPower Semiconductor MC2539 -25V -1A PNP Low VCEsat Transistor with N-channel Trench MOSFET **General Description** Features + Low collector-emitter saturation voltage $V_{\scriptscriptstyle CEsat}$ Combination of PNP low VCEsat Breakthrough In Small Signal transistor and N-channel Trench MOSFET.The + High collector current capability $I_{\rm c}$ and $I_{\rm \scriptscriptstyle CM}$ device is housed in a leadless medium power DFN2X2 • High collector current gain (h_{FE}) at high I_c Surface-Mounted Device (SMD) plastic package. • High energy efficiency due to less heat generation Smaller required Printed-Circuit Board(PCB) Applications area than for conventional transisitors

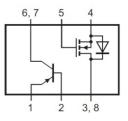
- · Loadswitch
- · Charging circuits
- · Power management · Battery-driven devices
- Power switches (e.g.motors.fans)







Simplified outline



Graphic symbol

Parameter	Units	Value	
Drain-Source Voltage (MOSFET)	30		
Collector-Emitter breakdown voltage (PNP Transistor)	-25		
Gate-Source Voltage (MOSFET)	±12	V	
Collector-Base breakdown voltage(PNP Transistor)	-40		
Emitter-Base breakdown voltage(PNP Transistor)	-5		
Continuous Drain Current(MOSFET) ^a	2.5		
Pulsed Drain Current (MOSFET) ^b	10	A	
Collector Current(PNP Transistor)	-1		
Diode Continuous Forward Current (MOSFET) ^a	1.7		
Total Dissipation (PNP Transistor)	0.8	W	
Maximum Junction Temperature(PNP Transistor and MOSFET)	150		
Storage Temperature Range(PNP Transistor and MOSFET)	-55 to 150	°C	
Soldering Recommendation (PeakTemperature)(PNP Transistor and MOSFET) ^c	260		
Thermal Resistance-Junction to Ambient At Steady State(MOSFET)	100		
Thermal Resistance-Junction to Ambient At Steady State(PNP Transistor)	110	°C/W	
Thermal Resistance-Junction to Ambient At Steady State(PNP Transistor) Notes: a.Surface Mounted on 1"x1" FR4 Board. b.Pulse test;pulse width≤300µs, duty cycle≤2%. c.Rework Conditions:manual soldering with a soldering iron is not recommended for leadless compone		°C	



MC2539

Packing Information

Device	Marking	Tape Width	Reel Size	Quantity
MC2539	D439 •××××	7"	8mm	3000 units

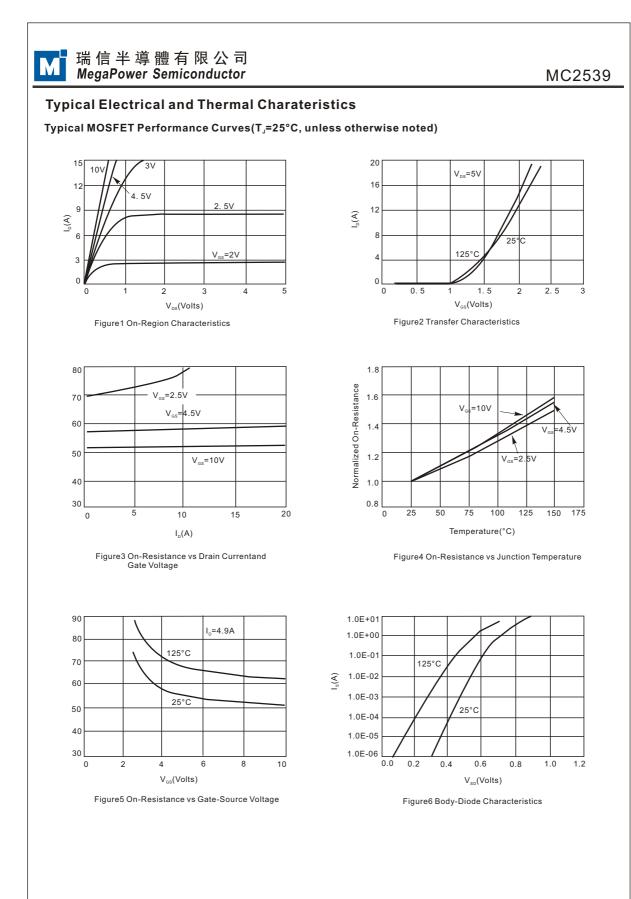
MOSFET Static and Dynamic Characteristics(Tj=25°C, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V,I _{DS} =250µA	30			
Gate Threshold Voltage	$V_{_{GS(th)}}$	V_{DS} =VGS,I _{DS} =-250µA	0.6	0.75	1.0	V
Gate Leakage Current	I _{GSS}	V_{DS} =0V, V_{GS} =±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS} V _{DS} =24V, V _{GS} =0V T _J =85 ^c	(-24)(1)(-0)(-1)(-1)(-1)(-1)(-1)(-1)(-1)(-1)(-1)(-1			1	μA
				30		
Drain-Source On-State Resistance	$R_{DS(ON)} = \frac{V_{GS}=4.5V, I_{DS}=2.5A}{V_{GS}=2.5V, I_{DS}=1.5A}$	V _{gs} =4.5V,I _{ds} =2.5A		80	100	mΩ
		V _{GS} =2.5V,I _{DS} =1.5A		90	120	11132
Diode Forward Voltage	V _{SD}	I_{sd} =1.7A, V_{gs} =0V		0.7	1.3	V

PNP Transistor Specifications (T_j=25°C Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
DC Current Cain(note)	$H_{FE(1)}$	V_{ce} =-1V,I _c =-100mA	85		400	
DC Current Gain(note)	$H_{\text{FE}(2)}$	V_{ce} =-1V,I _c =-800mA	40			
Transition Frequency	f _T	V _{ce} =-10V,I _c =-50mA,f=30MHz	100			Mhz
Collector cut-off Current	I _{cbo}	V _{CB} =-40V,I _E =0			-0.1	
Emitter cut-off Current	I _{ceo}	V _{ce} =-20V,I _e =0			-0.1	μA
Emitter cut-off Current	I _{EBO}	V _{EB} =-5V,I _c =0			-0.1	
Collector-bass breakdown voltage	V _{(BR)CBO}	I _c =-100μΑ,I _e =0	-40			V
Emitter breakdown voltage	V _{(BR)CBO}	I_{c} =-0.1mA, I_{B} =0	-25			V
Emitter-bass breakdown voltage	V _{(BR)CBO}	Ι _ε =-100μΑ,Ι _c =0	-5			V
Collector-emitter saturation voltage	V _{CE(sat)}	I _c =-800mA,I _B =-80mA			-0.4	V
Collector-emitter saturation voltage	V _{CE(sat)}	I _c =-500mA,I _B =-5mA			-0.6	V
Base-emitter saturation voltage	V _{BE(sat)}	I _c =-800mA,I _B =-80mA			-1.2	V
Base-emitter voltage	V _{BE(on)}	V _{ce} =-1V,I _c =-10mA			-1.0	V
Out capacitance	C _{ob}	V _{cb} =-10V,I _e =0mA,f=1MHz			20	pF

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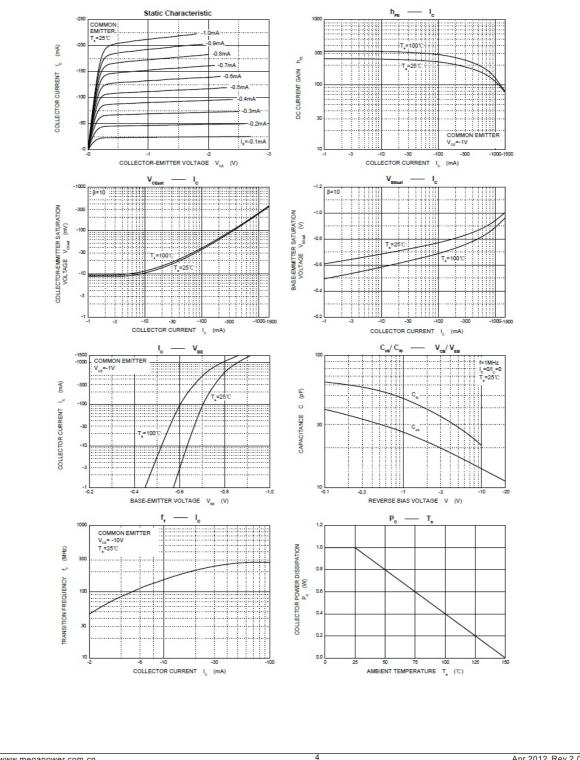


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Typical Electrical and Thermal Characteristics





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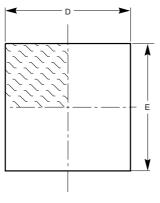


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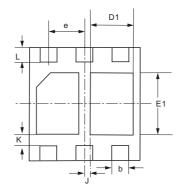
Package Outline

DFN2X2X0.75-6L

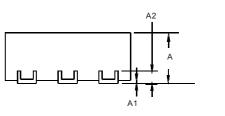




			Unit:mm	
Symbol	Min	Nom	Max	
А	0.70	0.75	0.80	
A1	0.00		0.05	
A2	0. 20REF			
b	0. 25	0.30	0.35	
D	2. 00BSC			
D1	0.60	0.65	0.70	
Е	2.00BSC			
E1	0.80	0.85	0.90	
е	0. 65BSC			
К	0. 25REF			
L	0. 25	0.30	0.35	
J	0. 15REF			



BOTTOM VIEW



SIDE VIEW

Notes:

(1)All dimensions are in millimeters.Angles in degree.(2)Package body size exclude mold flash and gate burrs.

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